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Research output

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Ostermann, T., Bacher, C., Schneider, D., Gut, W., Lackner, C., Koessl, R., Hagelauer, R., Deutschmann, B. & Jungreithmair, R., 2003, *International Symposium on Electromagnetic Compatibility.* ., p. 44-47

Characterization of the EME of Integrated Circuits with the Help of the IEC Standard 61967
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CMOS Output Driver with Reduced Ground Bounce and Electromagnetic Emission
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Darstellung der TEM-Zellen und der Surface Scan Messmethode zur Untersuchung des Einflusses von On-Chip Decoupling Kapazitäten auf die Störemission von Integrierten Schaltungen
Ostermann, T., Deutschmann, B., Schneider, D. & Jungreithmair, R., 2003, *ITG-Workshop Testmethods and Reliability of Circuits and Systems.* ., p. 66-69

Direct Power Injection (DPI) to Measure the Immunity of Integrated Circuits Against Conducted Disturbances
Deutschmann, B. & Ostermann, T., 2003, *International Mixed-Signal Testing Workshop.* ., p. 264-267

Effects of Skewing Output Driver Switching on the Electromagnetic Emission
Deutschmann, B., Jungreithmair, R. & Winkler, G., 2003, *IEEE Symposium on Electromagnetic Compatibility 2003.* ., p. 236-241

EMV-Charakterisierung von ICs (Die neuen Normen zurCharakterisierung der EMV integrierter Schaltungen)
Deutschmann, B., Winkler, G. & Jungreithmair, R., 2003, In: Test-Kompendium. 2003, p. 35-37

EMV in der Kraftfahrzeugtechnik (EMV-Anforderungen an elektrische/elektronische Komponenten und integrierte Schaltungen)
Lamedschwandner, K. & Deutschmann, B., 2003, In: EMC-Kompendium. p. 196-199

EMV-Messungen auf IC-Ebene gemäß den Normen IEC 61967 und IEC 62132
Ostermann, T. & Deutschmann, B., 2003, *ITG Diskussionssitzung Messverfahren der EMV (FA 9.1).* ., p. 70-73

Ground Bounce und Simultaneous Switching Noise
Ostermann, T., Tanda, A. & Deutschmann, B., 2003, *Beiträge der Informationstagung Mikroelektronik 2003.* Wien: Österreichischer Verband für Elektrotechnik, Vol. 33. p. 449-453 (ÖVE-Schriftenreihe).

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Deutschmann, B., 2003, *Analog Circuit Design: Fractional-N Synthesizers, Design for Robustness, Line and Bus Drivers.* Roermund, A., Steyaert, M. & Huijsing, J. H. (eds.). 1 ed. Boston, Mass. [u.a.]: Kluwer, p. 227-242

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Messmethode zur Messung der leitungsgeführten Störemission von ICs (Die Probleme mit der 150 Ohm Methode, IEC 61967-4)
Deutschmann, B., Winkler, G. & Jungreithmair, R., 2003, In: EMC-Kompendium. 2003, p. 174-176

Neue Burst-Generatoren zur Prüfung der Störfestigkeit von integrierten Schaltkreisen
Deutschmann, B., Langer, G. & Auderer, G., 2003, *Austrochip.* Linz: Inst. für Integrierte Schaltungen, Johannes-Kepler-Univ., p. 9-12

Störemission integrierter Schaltungen im Vergleich zur Störstrahlung elektronischer Geräte
Winkler, G., Deutschmann, B., Lamedschwandner, K. & Ostermann, T., 2003, *Beiträge der Informationstagung Mikroelektronik 2003.* Wien: Österreichischer Verband für Elektrotechnik, Vol. 33. p. 221-226 (ÖVE-Schriftenreihe).

TEM-Cell and Surface Scan to Identify the Electromagnetic Emission of Integrated Circuits
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Visualizing the Electromagnetic Emission at the Surface of ICs
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Bitte nicht stören! Störemission und Störfestigkeit von Kfzs
Deutschmann, B. & Lamedschwandner, K., 2002, In: Design & Elektronik. 3, p. 59-62

Characterization of Integrated Circuits Electromagnetic Emission with IEC 61967-4
Deutschmann, B., Winkler, G. & Jungreithmair, R., 2002, *International Symposium on Electromagnetic Compatibility.* ., p. 493-497

Characterization of the influence of different power supply styles on the electromagnetic emission of ICs by using the TEM-Cell method (IEC 61967-2)
Ostermann, T., Schneider, D., Bacher, C., Deutschmann, B., Jungreithmair, R., Gut, W., Lackner, C., Koessl, R. & Hagelauer, R., 2002, *International Workshop on Electromagnetic Compatibility of Integrated Circuits.* ., p. 57-60

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Lamedschwandner, K. & Deutschmann, B., 2002, In: Elektronik-Report. 11, p. 6-7

Let's get started, Starterkits erleichtern Elektronikentwicklung
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Measuring the Electromagnetic Emissions of Integrated Circuits with IEC 61967-4 ((The Measuring Method and its Weaknesses)
Deutschmann, B., Winkler, G. & Jungreithmair, R., 2002, *Symposium record ; vol. 1.* Piscataway, NY: IEEE, p. 407-412

Surface scan to pinpoint EMC problems
Deutschmann, B. & Jungreithmair, R., 2002, *Austrochip 2002.* Graz: Inst. für Elektronik, Techn. Univ. Graz, p. 73-77

Ungestörtes Fahrvergnügen? - EMV von Kfz-Elektronik
Deutschmann, B., 2002, *Begleittexte zum Entwicklerforum Kfz-Elektronik.* Poing: Design & Elektronik, p. 223-231

Untersuchung des Einflusses von On-Chip Decoupling Kapazitäten auf die Verringerung der Störemission von Integrierten Schaltungen
Ostermann, T., Schneider, D., Bacher, C., Deutschmann, B., Jungreithmair, R., Lackner, C., Koessl, R., Gut, W., Bauernfeind, T. & Hagelauer, R., 2002, *Kleinheubacher Tagung 2002.* ., p. ?-?

EMV-gerechte Entwicklung von integrierten Schaltkreisen
Deutschmann, B., 2001, In: EMV-ESD. 12, p. 11-13

EMV-gerechte Entwicklung von ITE-Geräten
Deutschmann, B. & Lamedschwandner, K., 2001, In: Design & verification. 12, 3, p. 22-25

EMV-gerecht Entwicklung von ITE-Geräten
Deutschmann, B. & Lamedschwandner, K., 2001, In: Telematik. 7, 1, p. 32-33

Moderate Slew Rate for Reducing the High Frequency Content
Deutschmann, B. & Winkler, G., 2001, *ISTET 01 ; Vol. 2.* Linz: ., p. 154-157

Moderate Slew Rate zur Reduzierung hochfrequenter Spektralanteile
Deutschmann, B. & Winkler, G., 2001, *Beiträge der Informationstagung ME 01.* Wien: Eigenverl. des Österr. Verb. für Elektrotechnik, Vol. 26. p. 333-338 (ÖVE-Schriftenreihe).

The Mythos Ground Bounce
Deutschmann, B., 2001, *Tagungsband.* Wien: Inst. für Computertechnik, TU Wien, p. 33-40

Activities

14th International Workshop on the Electromagnetic Compatibility of Integrated Circuits, EMC Compo 2024
Zupan, D. (Participant), Czepl, N. (Participant), Deutschmann, B. (Member of programme committee), Pfeifer, M. (Participant), Kircher, D. (Participant) & Hameed, M. (Participant)
7 Oct 2024 → 9 Oct 2024

20. EMV-Fachtagung 2023
Kircher, D. (Participant), Czepl, N. (Participant), Zupan, D. (Participant) & Deutschmann, B. (Participant)
27 Sept 2023 → 28 Sept 2023

2023 International Symposium and Exhibition on Electromagnetic Compatibility
Kircher, D. (Participant), Czepl, N. (Participant), Zupan, D. (Participant) & Deutschmann, B. (Participant)
4 Sept 2023 → 8 Sept 2023

2023 Joint Asia-Pacific International Symposium on Electromagnetic Compatibility and International Conference on ElectroMagnetic Interference and Compatibility
Kircher, D. (Participant), Czepl, N. (Participant), Deutschmann, B. (Participant) & Hansen, J. C. (Participant)
22 May 2023 → 25 May 2023

Industry Strategy Symposium Europe 2023
Deutschmann, B. (Participant) & Haubenwallner, C. (Participant)

15 Feb 2023 → 16 Feb 2023

Combined Investigations of Electromagnetic Compatibility and Environmental Effects
Deutschmann, B. (Speaker)
26 Nov 2022

Electronica 2022
Deutschmann, B. (Participant), Zupan, D. (Participant), Haubenwallner, C. (Participant), Koffler, S. (Participant), Czepl, N. (Participant) & Kircher, D. (Participant)
15 Nov 2022 → 18 Nov 2022

SEMICON Europa 2022
Deutschmann, B. (Participant), Zupan, D. (Participant), Haubenwallner, C. (Participant), Koffler, S. (Participant), Czepl, N. (Participant) & Kircher, D. (Participant)
15 Nov 2022 → 18 Nov 2022

Reduction of conducted emission through optimum placement and selection of decoupling capacitors
Deutschmann, B. (Speaker) & Winkler, G. (Speaker)
21 Sept 2022

19. EMV-Fachtagung 2022
Zupan, D. (Organiser), Winkler, G. (Organiser), Deutschmann, B. (Organiser), Odreitz, K. (Organiser), Kircher, D. (Participant), Czepl, N. (Participant), Koffler, S. (Participant) & Haubenwallner, C. (Participant)
20 Sept 2022 → 22 Sept 2022

IEEE EMC PhD Student Day 2022
Odreitz, K. (Organiser), Yildiz, Ö. F. (Organiser), Schuster, C. (Organiser), Deutschmann, B. (Organiser), Pommerenke, D. J. (Organiser), Czepl, N. (Participant), Esmaeili, H. (Participant), Fellner, G. (Participant), Gholizadeh, M. (Participant), Ghosalkar, S. (Participant), Kircher, D. (Participant), Mi, R. (Participant), Petzel, L. (Participant), Rammal, Y. (Participant), Schierholz, M. (Participant), Wulff, M. (Participant), Zhang, M. (Participant) & Zupan, D. (Participant)
20 Sept 2022 → 21 Sept 2022

2022 International Symposium on Electromagnetic Compatibility
Kircher, D. (Participant), Deutschmann, B. (Participant), Zupan, D. (Participant), Czepl, N. (Participant), Fellner, G. (Participant), Petzel, L. (Participant) & Pommerenke, D. J. (Participant)
5 Sept 2022 → 8 Sept 2022

Spread Spectrum Clocking (SSC) to Overcome EMI Issues
Deutschmann, B. (Speaker)
5 Sept 2022

Functional Safety Risks of Smart Power Devices due to EMI
Deutschmann, B. (Speaker) & Kircher, D. (Speaker)
13 Jul 2022

2022 International Exhibition and Conference on Electromagnetic Compatibility
Kircher, D. (Participant) & Deutschmann, B. (Participant)
12 Jul 2022 → 14 Jul 2022

17th International Conference on PhD Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Member)
12 Jun 2022 → 15 Jun 2022

Electromagnetic Emissions in Combination with TID Stress – Physical Background, Test Setup and First Results
Michalowska-Forsyth, A. M. (Speaker), Czepl, N. (Speaker) & Deutschmann, B. (Speaker)
26 Apr 2022

Electromagnetic Compatibility Essentials
Odreitz, K. (Contributor), Deutschmann, B. (Contributor) & Pommerenke, D. J. (Contributor)
22 Mar 2022

13th International Workshop on the Electromagnetic Compatibility of Integrated Circuits
Zupan, D. (Participant), Czepl, N. (Participant), Kircher, D. (Participant) & Deutschmann, B. (Participant)
9 Mar 2022 → 11 Mar 2022

Improving integrated circuit reliability by combining tests to ionizing radiation and electromagnetic compatibility
Vargas, F. (Speaker), Deutschmann, B. (Speaker), Ben Dhia, S. (Speaker), Czepl, N. (Speaker) & Michalowska-Forsyth, A. M. (Speaker)
3 Mar 2022

13th International Workshop on the Electromagnetic Compatibility of Integrated Circuits (Event)
Deutschmann, B. (Member)
1 Jan 2022 → 31 Dec 2022

2022 International Symposium on Electromagnetic Compatibility (Event)
Deutschmann, B. (Member)
1 Jan 2022 → 31 Dec 2022

Organisation des VWA/DA Preises der Fakultät für Elektrotechnik und Informationstechnik
Baunach, M. C. (Speaker), Saukh, O. (Speaker), Pommerenke, D. J. (Speaker) & Deutschmann, B. (Speaker)
2022

SEMICON Europa 2021
Zupan, D. (Participant), Deutschmann, B. (Participant), Kircher, D. (Participant), Czepl, N. (Participant) & Koffler, S. (Participant)
16 Nov 2021 → 19 Nov 2021

Elektrostatische Entladungen und Elektronik
Deutschmann, B. (Speaker), Winkler, G. (Speaker) & Pommerenke, D. J. (Speaker)
21 Oct 2021

2021 Asia-Pacific International Symposium on Electromagnetic Compatibility
Zupan, D. (Participant), Deutschmann, B. (Participant), Czepl, N. (Participant) & Michalowska-Forsyth, A. M. (Participant)
27 Sept 2021 → 30 Sept 2021

2021 Asia-Pacific International Symposium on Electromagnetic Compatibility (Event)
Deutschmann, B. (Peer reviewer)
27 Sept 2021 → 30 Sept 2021

2021 Asia-Pacific International Symposium on Electromagnetic Compatibility (Event)
Deutschmann, B. (Member)
27 Sept 2021 → 30 Sept 2021

Improving Integrated Circuit Reliability by Combining Tests to Ionizing Radiation and Electromagnetic Compatibility
Deutschmann, B. (Speaker), Michalowska-Forsyth, A. M. (Speaker), Czepl, N. (Speaker) & Vargas, F. (Speaker)
27 Sept 2021

2021 Asia-Pacific International Symposium on Electromagnetic Compatibility (Event)
Deutschmann, B. (Chair)
21 Sept 2021 → 30 Sept 2021

2021 Joint IEEE International Symposium on Electromagnetic Compatibility Signal and Power Integrity, and EMC Europe (Event)
Deutschmann, B. (Chair)
21 Jul 2021 → 21 Aug 2021

2021 International Conference on Synthesis, Modeling, Analysis and Simulation Methods and Applications to Circuit Design, and 16th Conference on PhD Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Member)
19 Jul 2021 → 22 Jul 2021

2021 International Conference on Synthesis, Modeling, Analysis and Simulation Methods and Applications to Circuit Design, and 16th Conference on PhD Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Peer reviewer)
19 Jul 2021 → 22 Jul 2021

2021 International Conference on Synthesis, Modeling, Analysis and Simulation Methods and Applications to Circuit Design, and 16th Conference on PhD Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Member)
19 Jul 2021 → 22 Jul 2021

13th International Workshop on the Electromagnetic Compatibility of Integrated Circuits (Event)
Deutschmann, B. (Member)
1 Jan 2021 → 31 Dec 2021

Panel discussion - METIS4Skills
Deutschmann, B. (Speaker)
18 Nov 2020

System Efficient ESD Design for Robust Electronic Systems
Deutschmann, B. (Speaker) & Pommerenke, D. J. (Speaker)
27 Oct 2020

2020 Austrochip Workshop on Microelectronics (Event)
Deutschmann, B. (Peer reviewer)
20 Oct 2020

2020 Austrochip Workshop on Microelectronics (Event)
Deutschmann, B. (Chair)
7 Oct 2020

Shielding Effectiveness of Soft Ferrite Materials
Deutschmann, B. (Speaker), Winkler, G. (Speaker), Khan, J. S. (Contributor) & Victoria, J. (Contributor)
30 Sept 2020

Einführung in das EMV-gerechte PCB- und Gerätedesign: Emissions- & Störfestigkeitsprobleme verstehen und beseitigen
Deutschmann, B. (Speaker) & Winkler, G. (Speaker)
29 Sept 2020

Microelectronic Systems Symposium 2020 (Event)
Deutschmann, B. (Member)
27 May 2020 → 28 May 2020

Asia-Pacific Symposium on Electromagnetic Compatibility (APEMC) (Event)
Deutschmann, B. (Peer reviewer)

19 May 2020 → 22 May 2020

Choosing the Right Decoupling Capacitor
Deutschmann, B. (Speaker) & Winkler, G. (Speaker)
13 Mar 2020

PCB-Design Guidelines to Reduce the Electromagnetic Emission
Deutschmann, B. (Speaker) & Winkler, G. (Speaker)
13 Mar 2020

27th Austrochip Workshop on Microelectronics (Event)
Deutschmann, B. (Peer reviewer)
24 Oct 2019

Comparison of Harmonic Suppression Techniques
Deutschmann, B. (Speaker)
22 Oct 2019

EMV-gerechtes Schaltungs- und Leiterplattendesign
Deutschmann, B. (Speaker) & Winkler, G. (Speaker)
16 Oct 2019

Ionizing Radiation and Electromagnetic Interference on Integrated Circuits: from the need of combined tests to current solutions
Deutschmann, B. (Speaker)
6 Sept 2019

Influence of impedance mismatch of bended or pinched cables on signal integrity
Bauer, S. M. (Speaker), Türk, C. (Contributor), Renhart, W. (Contributor), Biro, O. (Contributor), Maier, C. (Contributor), Winkler, G. (Contributor) & Deutschmann, B. (Contributor)
24 Jul 2019

Band Specific Suppression of Harmonics and its Effects on Power Efficiency
Deutschmann, B. (Speaker)
17 Jul 2019

15th Conference on Ph.D. Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Member)
15 Jul 2019 → 18 Jul 2019

15th Conference on Ph.D. Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Peer reviewer)
15 Jul 2019 → 18 Jul 2019

15th Conference on Ph.D. Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Member)
15 Jul 2019 → 18 Jul 2019

15th Conference on Ph.D. Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Peer reviewer)
15 Jul 2019 → 18 Jul 2019

How smart are smart power products under EMI?
Deutschmann, B. (Speaker)
23 May 2019

4. Sitzung des Programmbeirats der Silicon Austria Labs (SAL) (Event)
Deutschmann, B. (Member)
14 May 2019 → 15 May 2019

5. Sitzung des Programmbeirats der Silicon Austria Labs (SAL) (Event)
Deutschmann, B. (Chair)
14 May 2019 → 15 May 2019

6. Sitzung des Programmbeirats der Silicon Austria Labs (SAL) (Event)
Deutschmann, B. (Member)
14 May 2019 → 15 May 2019

BCI-Tests - Durchführung und Herausforderung
Deutschmann, B. (Speaker) & Winkler, G. (Speaker)
28 Feb 2019

Debugging EMC Problems with Oscilloscopes
Fuchs, M. (Speaker), Deutschmann, B. (Speaker) & Herdin, M. (Speaker)
27 Feb 2019

15th Conference on Ph.D. Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Peer reviewer)
1 Jan 2019 → 31 Dec 2019

27th Austrochip Workshop on Microelectronics (Event)
Deutschmann, B. (Member)
1 Jan 2019

Österreichischer Verband für Elektrotechnik (OVE) (External organisation)
Deutschmann, B. (Member)
1 Jan 2019 → 31 Dec 2019

The 12th International Workshop on the Electromagnetic Compatibility of Integrated Circuits (Event)
Deutschmann, B. (Member)
1 Jan 2019 → 31 Dec 2019

The 12th International Workshop on the Electromagnetic Compatibility of Integrated Circuits (Event)
Deutschmann, B. (Member)
1 Jan 2019 → 31 Dec 2019

Simulation of the Electromagnetic Emission of Electronic Systems
Deutschmann, B. (Organiser), Winkler, G. (Organiser) & Fuchs, M. (Organiser)
20 Dec 2018

Olivier Gevin
Michalowska-Forsyth, A. M. (Host), Deutschmann, B. (Host) & Bezhenova, V. (Host)
10 Dec 2018

Radiation Hardness Day
Michalowska-Forsyth, A. M. (Organiser), Deutschmann, B. (Organiser), Bezhenova, V. (Organiser), Vincenzi, T. (Participant) & Vorderderfler, M. (Participant)
10 Dec 2018

EMV-gerechtes Schaltungs- und Leiterplattendesign
Deutschmann, B. (Speaker) & Winkler, G. (Speaker)
16 Oct 2018

26th Austrian Workshop on Microelectronics
Söser, P. (Organiser), Auer, M. (Organiser), Lanz, E. (Organiser), Bezhenova, V. (Organiser), Michalowska-Forsyth, A. M. (Organiser), Dorner, E. (Organiser), Eisenkölbl, D. (Organiser), Fink, S. (Organiser), Reisenhofer, T. (Organiser), Lilek, R. (Organiser) & Deutschmann, B. (Organiser)
27 Sept 2018

3. Sitzung des Programmbeirats Silicon Austria Errichtungs GmbH (Event)
Deutschmann, B. (Member)
24 Sept 2018 → 25 Sept 2018

44th European Solid-State Circuits Conference
Deutschmann, B. (Organiser) & Wicht, B. (Organiser)
3 Sept 2018

Introduction to Robust Automotive IC Design and Electromagnetic Compatibility of ICs
Deutschmann, B. (Speaker) & Winkler, G. (Speaker)
3 Sept 2018

Investigation of Spice Models for Overvoltage Protection Devices with Respect to Fast Transients
Bauer, S. M. (Speaker), Renhart, W. (Contributor), Biro, O. (Contributor), Türk, C. (Contributor), Maier, C. (Contributor), Winkler, G. (Contributor) & Deutschmann, B. (Contributor)
1 Aug 2018

13th Conference on Ph.D. Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Peer reviewer)
2 Jul 2018 → 5 Jul 2018

13th Conference on Ph.D. Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Member)
2 Jul 2018 → 5 Jul 2018

14th Conference on Ph.D. Research in Microelectronics and Electronics, PRIME 2018 (Event)
Deutschmann, B. (Peer reviewer)
2 Jul 2018 → 5 Jul 2018

Wie „smart“ ist Smart Power Leistungselektronik unter Störbeeinflussung?
Deutschmann, B. (Speaker), Winkler, G. (Speaker) & Kastner, P. (Speaker)
12 Jun 2018 → 13 Jun 2018

14th Conference on Ph.D. Research in Microelectronics and Electronics, PRIME 2018 (Event)
Deutschmann, B. (Member)
2 Jun 2018 → 5 Jun 2018

Time domain FEM computational approach for calibration of surface scan method
Bauer, S. M. (Speaker), Biro, O. (Contributor), Koczka, G. (Contributor), Gleinser, A. (Contributor), Winkler, G. (Contributor) & Deutschmann, B. (Contributor)
16 May 2018

2018 JOINT IEEE INTERNATIONAL SYMPOSIUM ON ELECTROMAGNETIC COMPATIBILITY AND ASIA-PACIFIC SYMPOSIUM ON ELECTROMAGNETIC COMPATIBILITY (Event)

Deutschmann, B. (Chair)
14 May 2018 → 17 May 2018

2. Sitzung des Programmbeirats Silicon Austria Errichtungs GmbH (Event)
Deutschmann, B. (Member)
25 Apr 2018

Lange Nacht der Forschung 2018
Bezhenova, V. (Organiser), Michalowska-Forsyth, A. M. (Organiser), Deutschmann, B. (Organiser), Fuchs, M. (Organiser), Winkler, G. (Organiser), Auinger, B. (Organiser), Scherzer, M. (Organiser), Dorner, E. (Organiser), Fink, S. (Organiser), Eisenkölbl, D. (Organiser), Reisenhofer, T. (Organiser), Juch, N. (Organiser) & Söser, P. (Organiser)
13 Apr 2018

Locating EMC problems at the surface of ICs and PCBs
Deutschmann, B. (Speaker)
13 Apr 2018

Electromagnetic Compatibility of Integrated Circuits – An Introduction to EMC Test Methods
Deutschmann, B. (Speaker)
12 Mar 2018 → 16 Mar 2018

Gridconv - Innovativer HVDC/DC Converter für HVDC-Netze
Auinger, B. (Contributor), Deutschmann, B. (Contributor), Schichler, U. (Contributor), Krischan, K. (Contributor), Horn, M. (Contributor), Reichhartinger, M. (Contributor) & Renner, H. (Speaker)
14 Feb 2018

1. Sitzung des Programmbeirats Silicon Austria Errichtungs GmbH (Event)
Deutschmann, B. (Member)
8 Feb 2018

Österreichischer Verband für Elektrotechnik (OVE) (External organisation)
Deutschmann, B. (Member)
1 Jan 2018 → 31 Dec 2018

Fabian Vargas
Bezhenova, V. (Host) & Deutschmann, B. (Host)
11 Dec 2017

Introduction into Electromagnetic Compatibility
Auinger, B. (Speaker), Deutschmann, B. (Speaker), Winkler, G. (Speaker) & Fuchs, M. (Speaker)
21 Nov 2017 → 22 Nov 2017

25th Austrian Workshop on Microelectronics (Event)
Deutschmann, B. (Peer reviewer)
12 Oct 2017

11th International Workshop on the Electromagnetic Compatibility of Integrated Circuits (Event)
Deutschmann, B. (Member)
4 Jul 2017 → 8 Jul 2017

11th International Workshop on the Electromagnetic Compatibility of Integrated Circuits (Event)
Deutschmann, B. (Peer reviewer)
4 Jul 2017 → 8 Jul 2017

11th International Workshop on the Electromagnetic Compatibility of Integrated Circuits (Event)
Deutschmann, B. (Peer reviewer)
4 Jul 2017 → 8 Jul 2017

8th Workshop on Electromagnetic Compatibility of Integrated Circuits (EMC Compo 2011) (Event)
Deutschmann, B. (Peer reviewer)
4 Jul 2017 → 8 Jul 2017

8th Workshop on Electromagnetic Compatibility of Integrated Circuits (EMC Compo 2011) (Event)
Deutschmann, B. (Member)
4 Jul 2017 → 8 Jul 2017

2017 Asia-Pacific International Symposium on Electromagnetic Compatibility, APEMC 2017 (Event)
Deutschmann, B. (Peer reviewer)
20 Jun 2017 → 23 Jun 2017

13th Conference on Ph.D. Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Member)
12 Jun 2017 → 15 Jun 2017

GriDConv: HVDC-DC Converter for High Voltage Direct Current Transmission Systems – Background and Design
Krischan, K. (Speaker), Auinger, B. (Speaker), Schichler, U. (Speaker), Deutschmann, B. (Speaker) & Renner, H. (Speaker)
26 Apr 2017

GriDConv: HVDC-DC Converter for High Voltage Direct Current Transmission Systems – The Electronic System
Auinger, B. (Speaker), Vollmaier, F. (Speaker), Deutschmann, B. (Speaker), Krischan, K. (Speaker) & Schichler, U. (Speaker)
26 Apr 2017 → 27 Apr 2017

Störemission von Leistungselektronik
Deutschmann, B. (Contributor), Winkler, G. (Contributor) & Auinger, B. (Contributor)
26 Apr 2017

Leistungselektronikschau im Rahmen der 15. EMV - Fachtagung
Muetze, A. (Organiser) & Deutschmann, B. (Organiser)
16 Apr 2017

Österreichischer Verband für Elektrotechnik (OVE) (External organisation)
Deutschmann, B. (Member)
1 Jan 2017 → 31 Dec 2017

Susceptibility of Precision Operational Amplifiers to EMI
Deutschmann, B. (Speaker)
30 Nov 2016

Erfolgreich führen und kommunizieren
Deutschmann, B. (Participant)
24 Nov 2016

Arbeitsrecht für wissenschaftliche Führungskräfte
Deutschmann, B. (Participant)
15 Nov 2016

LTSpice Seminar with Mike Engelhardt
Deutschmann, B. (Participant)
28 Oct 2016

24th Austrian Workshop on Microelectronics
Deutschmann, B. (Participant)
19 Oct 2016

12th Conference on Ph.D. Research in Microelectronics and Electronics
Deutschmann, B. (Participant)
27 Jun 2016 → 30 Jun 2016

12th Conference on Ph.D. Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Member)
27 Jun 2016 → 30 Jun 2016

12th Conference on Ph.D. Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Peer reviewer)
27 Jun 2016 → 30 Jun 2016

12th Conference on Ph.D. Research in Microelectronics and Electronics (Event)
Deutschmann, B. (Member)
27 Jun 2016 → 30 Jun 2016

Spread Spectrum Clocking for Emission Reduction
Deutschmann, B. (Speaker)
15 Jun 2016

Inauguration and Radhard Symposium
Deutschmann, B. (Participant)
7 Jun 2016 → 8 Jun 2016

Asia-Pacific International Symposium on Electromagnetic Compatibility & Signal Integrity (APEMC)
Deutschmann, B. (Participant)
17 May 2016 → 21 May 2016

14. EMV Fachtagung
Deutschmann, B. (Speaker)
12 Apr 2016

Power Supply Meets EMC-Know How
Deutschmann, B. (Participant)
16 Feb 2016

Expertenworkshop "Sensorik / Mikroelektronik" im Rahmen des HTS Strategieentwicklungsprozesses
Deutschmann, B. (Participant)
10 Feb 2016

Österreichischer Verband für Elektrotechnik (OVE) (External organisation)
Deutschmann, B. (Member)
1 Jan 2016 → 31 Dec 2016

Digital Control Strategies for EMI reduced switching of Smart Power Switches
Deutschmann, B. (Agent)
18 Dec 2015

10th International Workshop on the Electromagnetic Compatibility of Integrated Circuits, EMC Compo 2015 (Event)
Deutschmann, B. (Member)
10 Nov 2015 → 15 Nov 2015

10th International Workshop on the Electromagnetic Compatibility of Integrated Circuits, EMC Compo 2015 (Event)
Deutschmann, B. (Peer reviewer)
10 Nov 2015 → 13 Nov 2015

International Workshop on the Electromagnetic Compatibility of Integrated Circuits (EMC Compo) (Event)
Deutschmann, B. (Peer reviewer)
10 Nov 2015 → 13 Nov 2015

International Symposium on Electromagnetic Compatibility
Deutschmann, B. (Speaker)
16 Aug 2015 → 22 Aug 2015

Asia-Pacific International Symposium on Electromagnetic Compatibility (Event)
Deutschmann, B. (Peer reviewer)
25 May 2015 → 29 May 2015

Österreichischer Verband für Elektrotechnik (OVE) (External organisation)
Deutschmann, B. (Member)
1 Jan 2015 → 31 Dec 2015

Austrian Workshop on Microelectronics (Austrochip) (Event)
Deutschmann, B. (Peer reviewer)
14 Oct 2014

AMP-S Design Symposium
Deutschmann, B. (Speaker)
14 May 2014

Microelectronics Systems Symposium, MESS
Deutschmann, B. (Speaker)
9 May 2014 → 10 May 2014

Österreichischer Verband für Elektrotechnik (OVE) (External organisation)
Deutschmann, B. (Member)
1 Jan 2014 → 31 Dec 2014

9th International Workshop on Electromagnetic Compatibility of Integrated Circuits (Event)
Deutschmann, B. (Peer reviewer)
15 Dec 2013 → 18 Dec 2013

9th International Workshop on Electromagnetic Compatibility of Integrated Circuits (Event)
Deutschmann, B. (Member)
15 Dec 2013 → 18 Dec 2013

Austrochip 2013, 21st Austrian Workshop on Microelectronics
Deutschmann, B. (Speaker)
10 Oct 2013

8th Workshop on Electromagnetic Compatibility of Integrated Circuits (EMC Compo 2011) (Event)
Deutschmann, B. (Peer reviewer)
6 Nov 2011 → 9 Nov 2011

EMC Compo 2009 (Event)
Deutschmann, B. (Peer reviewer)
17 Nov 2009 → 19 Nov 2009

EMC Compo 2009 (Event)
Deutschmann, B. (Peer reviewer)
17 Nov 2009 → 18 Nov 2009

EMC Compo 2009 (Event)
Deutschmann, B. (Member)
17 Nov 2009 → 18 Nov 2009

EMC Compo 2009 (Event)
Deutschmann, B. (Member)
17 Nov 2009 → 19 Nov 2009

EMC Compo 2009 (Event)
Deutschmann, B. (Member)
17 Nov 2009 → 19 Nov 2009

EMC Compo 2009 (Event)
Deutschmann, B. (Peer reviewer)
17 Nov 2009 → 19 Nov 2009

Projects

Absorbers - Electronics Measurements with Absorbers
Deutschmann, B. (Co-Investigator (CoI))
17/04/19 → 22/05/20

ARCADE - New and extended dynamic pulse test concepts for integrated and discrete power semiconductors
Deutschmann, B. (Co-Investigator (CoI))
1/05/24 → 30/04/27

Cotomics - Computed Tomography IC with high Radiation immunity
Deutschmann, B. (Co-Investigator (CoI)) & Michalowska-Forsyth, A. M. (Co-Investigator (CoI))
1/02/15 → 30/11/18

Dissertation Schneider - Evaluation of variables influencing the lifetime of resonant MEMS mirrors by means of current measurements
Deutschmann, B. (Co-Investigator (CoI))
1/09/23 → 31/08/26

Electromagnetic Compatibility
Deutschmann, B. (Co-Investigator (CoI)) & Winkler, G. (Co-Investigator (CoI))
1/01/95 → 31/12/24

Electronic Circuit Design
Deutschmann, B. (Co-Investigator (CoI))
1/01/95 → 31/12/24

EM2APS - Enhanced Materials, Methods & Applications for Power Devises & Systems
Deutschmann, B. (Co-Investigator (CoI))
1/10/14 → 30/09/17

EMV-Geräte - EMC-compliant device development
Deutschmann, B. (Co-Investigator (CoI))
1/08/24 → 31/07/25

EMV Support - Electromagnetic compatibility Support
Deutschmann, B. (Co-Investigator (CoI))
26/08/21 → 30/09/22

ESD PROMEMO - ESD-Schutzstrukturentwurf und Prototyping, Messung und Modellierung
Deutschmann, B. (Co-Investigator (CoI))
1/08/21 → 30/06/22

EU - NanoCaTe - Nano-carbons for versatile power supply modules
Kappel, R. (Co-Investigator (CoI)) & Deutschmann, B. (Co-Investigator (CoI))
1/10/13 → 30/09/17

FPES2020 - Future of Power Electronic Systems 2020
Deutschmann, B. (Co-Investigator (CoI))
1/05/15 → 30/04/18

Inno-EBS - Interdisciplinary knowledge transfer in Electronic Based Systems (EBS) to strengthen value chain actors
Deutschmann, B. (Co-Investigator (CoI)), Jandl, M. (Co-Investigator (CoI)) & Kreuzer, E. (Co-Investigator (CoI))
1/02/20 → 31/07/23

METIS - MicroElectronics Training, Industry and Skills
Deutschmann, B. (Co-Investigator (CoI))
1/01/20 → 31/12/23

PREMI - Pre-estimation of electromagnetic interference of electronic based systems
Deutschmann, B. (Co-Investigator (CoI))
1/01/22 → 30/06/24

R-MULTICHARM - Multidisciplinary Characterization & Modeling for Innovative Process & Product Integration
Radl, S. (Co-Investigator (CoI)), Rosenauer, P. (Co-Investigator (CoI)) & Deutschmann, B. (Co-Investigator (CoI))
1/03/21 → 29/02/24

Robust SiC - Robust Multi-Channel Application Stress Concept for New High Power Semiconductor Technologies
Deutschmann, B. (Co-Investigator (CoI))
1/03/19 → 28/02/22

Smart Power ASICs - Evaluation and assessment of malfunctions of operated Smart Power ASICs during ESD gunshot tests. Development of measurement methods, laboratory analyses and design measures for robust design.
Deutschmann, B. (Co-Investigator (CoI))
1/02/25 → 31/01/28